

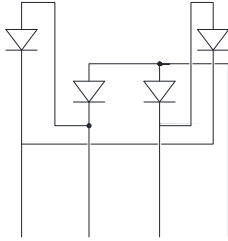
## Bridge Rectifiers

### Features

- UL recognition, file #E230084
- Glass passivated chip junction
- Thin single in-line package
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

### Typical Applications

General purpose use in AC/DC bridge full wave rectification for switching power supply, home appliances, office equipment, industrial automation applications.



### Mechanical Data

#### Package: PB

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free

**Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102

**Polarity:** As marked on body

### Maximum Ratings (T<sub>a</sub>=25 Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	PB5010H
Device marking code			PB5010H
Maximum Repetitive Peak Reverse Voltage	VRRM	V	1600
Maximum RMS Voltage	VRMS	V	1120
Maximum DC blocking Voltage	VDC	V	1600
Average rectified output current @60Hz sine wave, R-load,	I <sub>O</sub>	A	With heatsink T <sub>c</sub> =90
			Without heatsink T <sub>a</sub> =25
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, T <sub>j</sub> =25	IFSM	A	500
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, T <sub>j</sub> =25			1000
Current squared time @1ms t 8.3ms T <sub>j</sub> =25, Rating of per diode	I <sup>2</sup> t	A <sup>2</sup> s	1037.5
Storage temperature	T <sub>stg</sub>		-55 ~ +150
Junction temperature	T <sub>j</sub>		-55 ~ +150
Dielectric strength @ Terminals to case, AC 1 minute	V <sub>dis</sub>	KV	2.5
Mounting torque @Recommend torque 5kg cm	Tor	kg cm	8

### Electrical Characteristics T<sub>a</sub>=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	PB5010H
Maximum instantaneous forward voltage drop per diode	V <sub>F</sub>	V	I <sub>FM</sub> =25.0A	1.1
Maximum DC reverse current at rated DC blocking voltage per diode	I <sub>R</sub>	μA	T <sub>j</sub> =25	5
			T <sub>j</sub> =125	1000
Typical junction capacitance	C <sub>j</sub>	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	195



# PB5010H

## Thermal Characteristics $T_a=25$ Unless otherwise specified

PARAMETER		SYMBOL	UNIT	PB5010H
Thermal Resistance	Between junction and ambient, Without heatsink	$R_{JA}$	/W	15.0
	Between junction and case, With heatsink	$R_{JC}$		0.6

Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

## Ordering Information (Example)

PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
PB5010H	B1	Approximate 7.5	15	750	1500	TUBE

## Characteristics (Typical)

FIG1:Io-Tc Curve

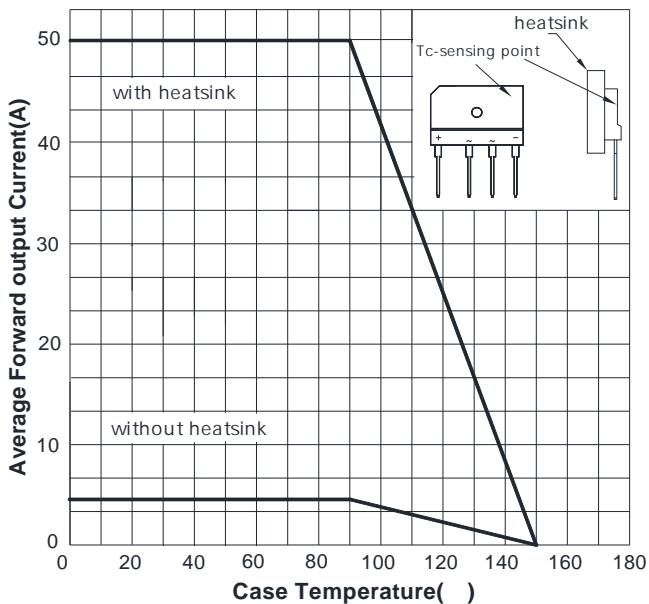


FIG2:Surge Forward Current Capability

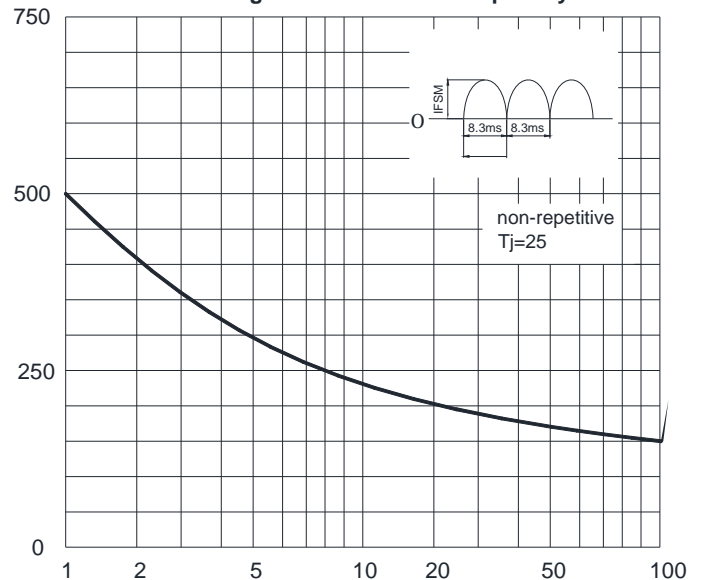


FIG3: Typical Forward Voltage

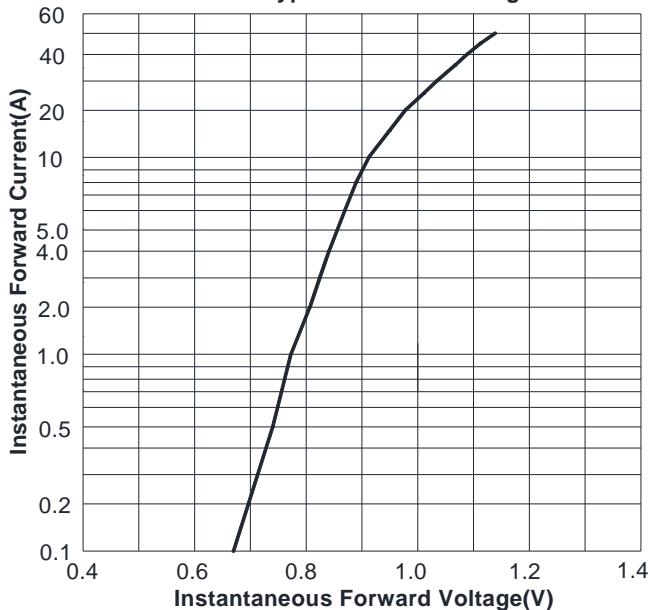
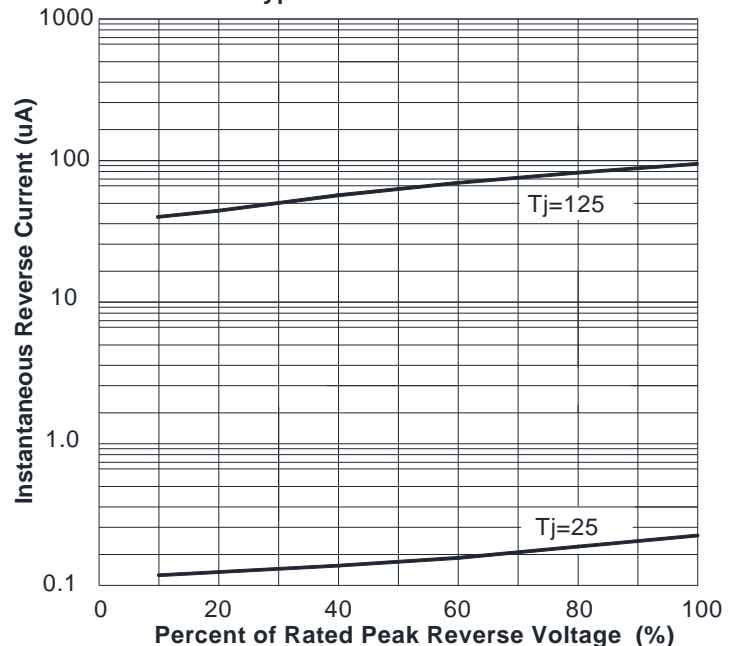
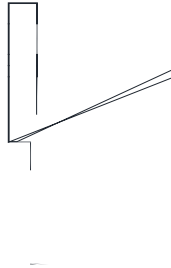
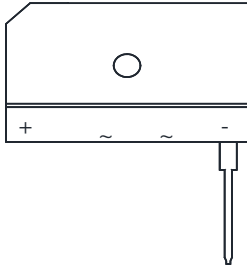


FIG4:Typical Reverse Characteristics





Outline Dimensions



PB		
Dim	Min	Max
A	29.7	30.3
B	19.7	20.3
C	17.0	18.0
D	4.8	5.8
E	3.8	4.2
F	7.3	7.7
G	9.8	10.2
H	0.9	1.1
I	2.0	2.4
J	2.3	2.7
K	3.4	3.8
L	4.4	4.8
M	10.8	11.2
N	3.1	3.7
O	3.1	3.4
P	0.6	0.8
A1	28.75	29.15
B1	18.75	19.15
C1	0.3	0.7
D1	0.3	0.7

Dimensions in millimeters



## Disclaimer

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